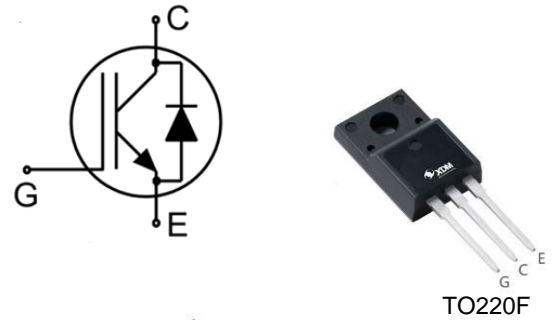


Trench Field-Stop Technology IGBT

Features

- 650V, 6A
- $V_{CE(sat)(typ.)} = 1.75V @ V_{GE}=15V, I_C=6A$
- Maximum Junction Temperature 175°C
- Pb-free Lead Plating; RoHS Compliant



Applications

- Solar Converters
- Uninterrupted Power Supply
- Welding Converters
- Mid to High Range Switching Frequency Converters



Key Performance and Package Parameters

Order codes	V_{CE}	I_C	$V_{CEsat}, T_{vj}=25^\circ C$	T_{vjmax}	Marking	Package
XD006H065CX2H3	650V	6A	1.75V	175°C	D6H65CX2	TO220F-3L
XD006H065CX2R3	650V	6A	1.75V	175°C	D6H65CX2	TO263-2L
XD006H065CX2G3	650V	6A	1.75V	175°C	D6H65CX2	TO252-2L

Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-Emitter Voltage	650	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Continuous Collector Current ($T_C=25^\circ C$)	12	A
	Continuous Collector Current ($T_C=100^\circ C$)	6	A
I_{CM}	Pulsed Collector Current (Note 1)	18	A
I_F	Diode Continuous Forward Current ($T_C=25^\circ C$)	12	A
	Diode Continuous Forward Current ($T_C=100^\circ C$)	6	A
I_{FM}	Diode Maximum Forward Current	18	A
P_D	Maximum Power Dissipation ($T_C=25^\circ C$) (Note 2)	89	W
	Maximum Power Dissipation ($T_C=100^\circ C$) (Note 2)	44	W
T_J	Operating Junction Temperature Range	-40 to 175	°C
T_{STG}	Storage Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Conditions	Max.	Unit
R _{θJC}	Thermal Resistance, Junction to Case for IGBT	TO220F-3L	3.6	°C/W
		TO263-2L	1.6	°C/W
		TO252-2L	1.6	°C/W
R _{θJC}	Thermal Resistance, Junction to Case for Diode	TO220F-3L	3.7	°C/W
		TO263-2L	2.6	°C/W
		TO252-2L	2.2	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient	TO220F-3L	66	°C/W
		TO263-2L	60	°C/W
		TO252-2L	78	°C/W

Electrical Characteristics (T_c=25°C unless otherwise noted.)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{CES}	Collector-Emitter Breakdown Voltage	V _{GE} =0V, I _C =200uA	650	---	---	V
I _{CES}	Collector-Emitter Leakage Current	V _{CE} =650V, V _{GE} =0V	---	---	40	uA
I _{GES}	Gate Leakage Current, Forward	V _{GE} =20V, V _{CE} =0V	---	---	100	nA
	Gate Leakage Current, Reverse	V _{GE} =-20V, V _{CE} =0V	---	---	100	nA
V _{GE(th)}	Gate Threshold Voltage	V _{GE} =V _{CE} , I _C =200uA	4.8	5.8	6.8	V
V _{CE(sat)}	Collector-Emitter Saturation Voltage	V _{GE} =15V, I _C =6A, T _j =25°C	---	1.75	2.10	V
		V _{GE} =15V, I _C =6A, T _j =150°C	---	2.05	---	V
Q _G	Total Gate Charge	V _{CC} =400V	---	11.5	---	nC
Q _{GE}	Gate-Emitter Charge	V _{GE} =15V	---	3.5	---	nC
Q _{GC}	Gate-Collector Charge	I _C =6A	---	3.5	---	nC
t _{d(on)}	Turn-on Delay Time	V _{CC} =400V V _{GE} =±15V I _C =6A R _G =10Ω Inductive Load T _C =25°C	---	12.5	---	ns
t _r	Turn-on Rise Time		---	6.4	---	ns
t _{d(off)}	Turn-off Delay Time		---	14.5	---	ns
t _f	Turn-off Fall Time		---	158	---	ns
E _{on}	Turn-on Switching Loss		---	95	---	uJ
E _{off}	Turn-off Switching Loss		---	98	---	uJ
E _{ts}	Total Switching Loss		---	193	---	uJ

C _{ies}	Input Capacitance	V _{CE} =25V V _{GE} =0V f =1MHz	---	313	---	pF
C _{oes}	Output Capacitance		---	34	---	pF
C _{res}	Reverse Transfer Capacitance		---	5	---	pF
SCSOA	Short Circuit Safe Operation Area	V _{GE} =15V, V _{CC} ≤400V, T _{J,start} ≤25°C	7	---	---	us

Diode Characteristics (T_C=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
V _F	Diode Forward Voltage	I _F =6A, T _J =25°C	---	1.65	2.10	V
		I _F =6A, T _J =150°C	---	1.48		V
t _{rr}	Diode Reverse Recovery Time	VR=400V	---	46.5	---	ns
I _{rr}	Diode peak Reverse Recovery Current	I _F =6A dI _F /dt=20A/us	---	0.35	---	A
Q _{rr}	Diode Reverse Recovery Charge	T _C =25°C	---	8.5	---	nC

Note1: Repetitive rating, pulse width limited by maximum junction temperature

Note2: For TO-263

Typical Characteristics

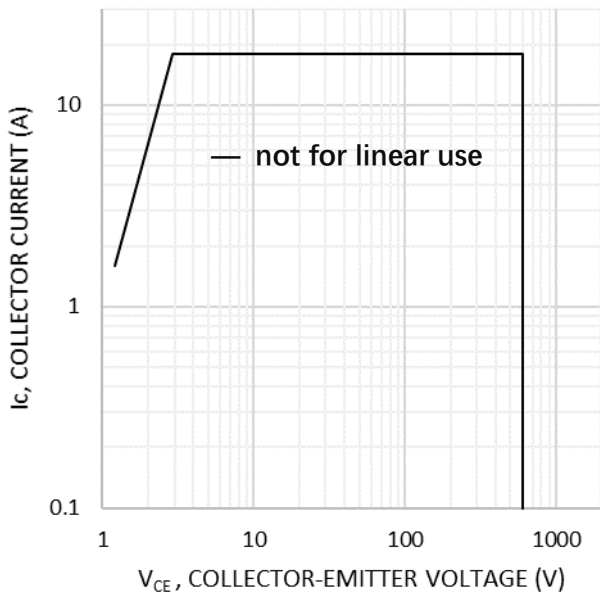


Fig. 1 Forward bias safe operating area (D=0, $T_C=25^\circ\text{C}$, $T_{vj}\leq 175^\circ\text{C}$; $V_{GE}=15\text{V}$)

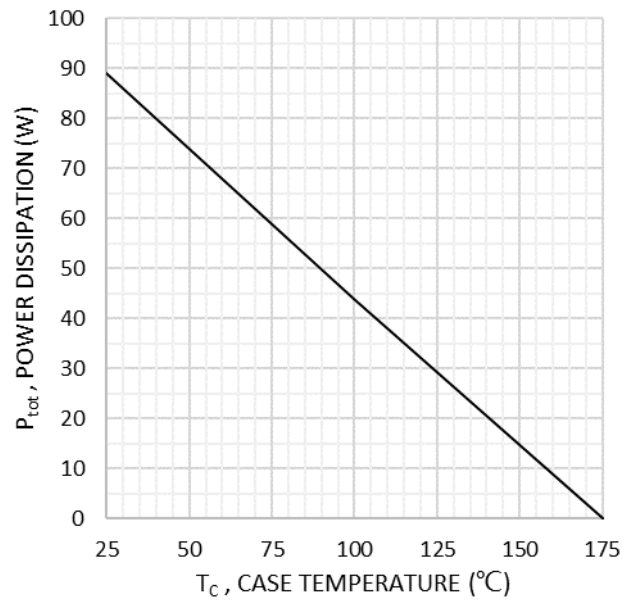


Fig. 2 Power dissipation as a function of case temperature ($T_{vj}\leq 175^\circ\text{C}$)

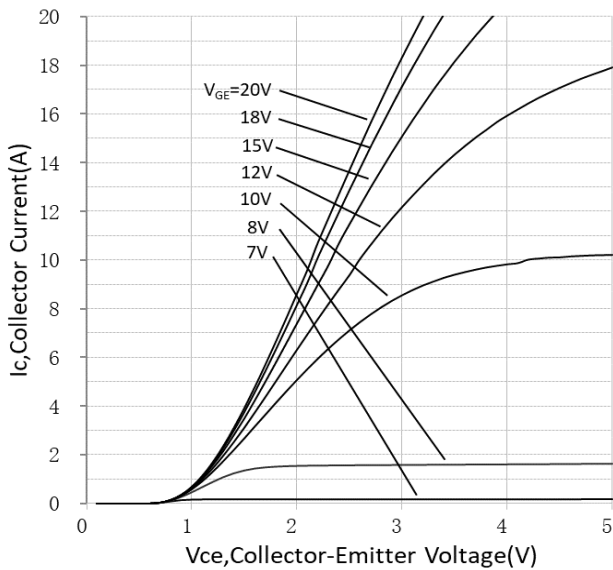


Fig. 3 Typical output characteristic ($T_{vj}=25^\circ\text{C}$)

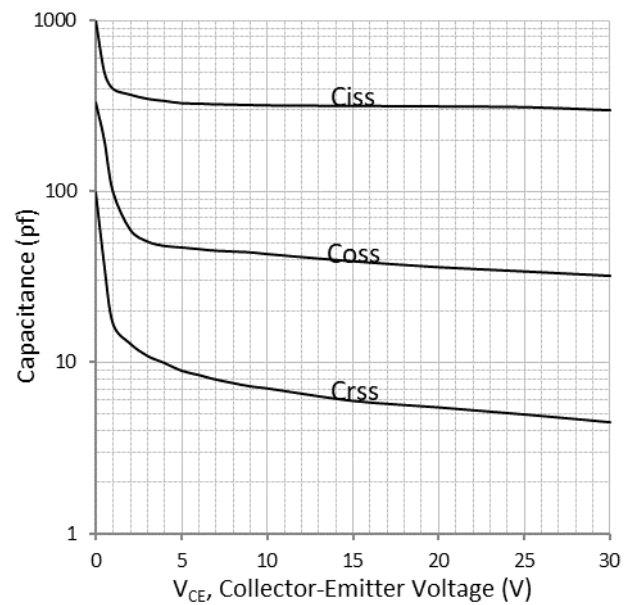


Fig. 4 Typical capacitance as a function of collector-emitter voltage ($V_{GE}=0\text{V}$, $f=1\text{MHz}$)

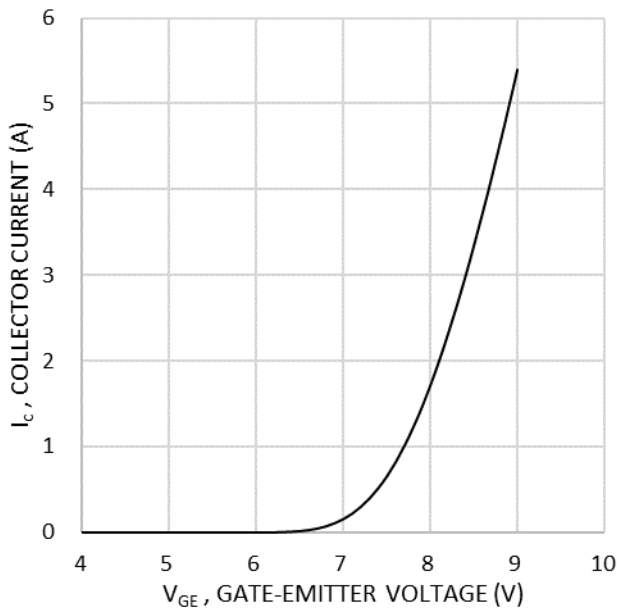


Fig. 5 Typical transfer characteristics ($V_{CE}=10V$)

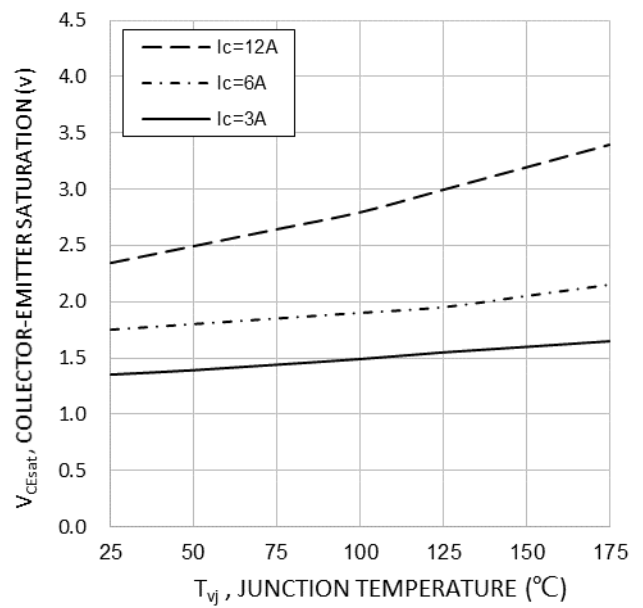


Fig. 6 Typical collector-emitter saturation voltage as a function of junction temperature ($V_{GE}=15V$)

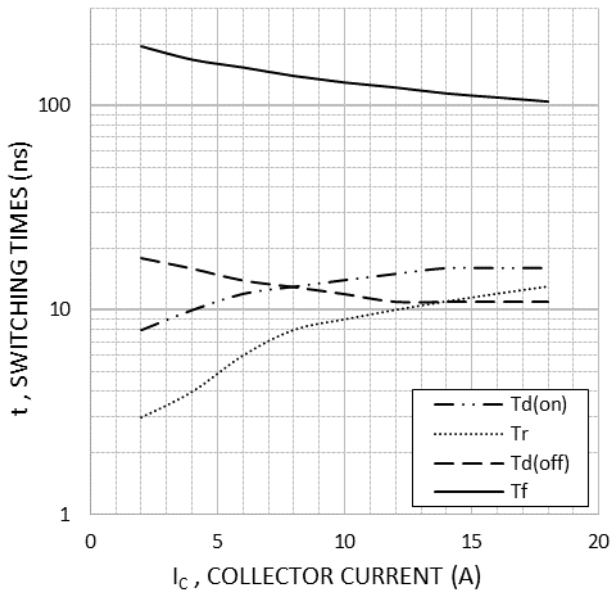


Fig. 7 Typical switching times as a function of collector current (inductive load, $T_{yj}=25^{\circ}C$, $V_{CE}=400V$, $V_{GE}=15/0V$, $r_G=10\Omega$)

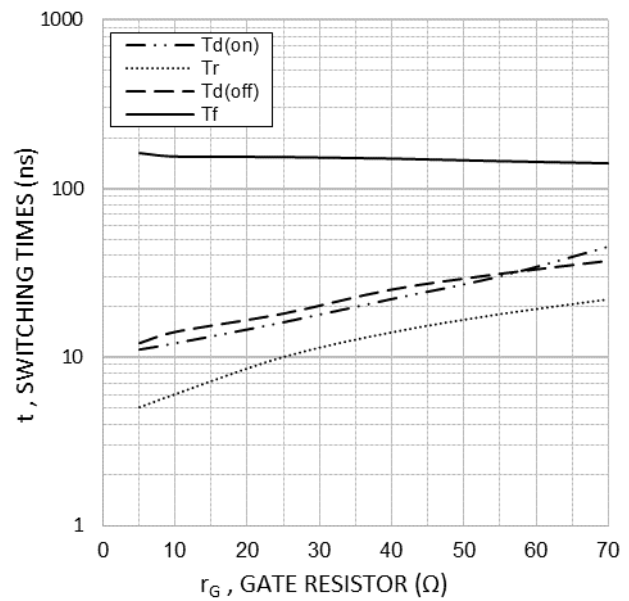


Fig. 8 Typical switching times as a function of gate resistor (inductive load, $T_{yj}=25^{\circ}C$, $V_{CE}=400V$, $V_{GE}=15/0V$, $I_c=6A$)

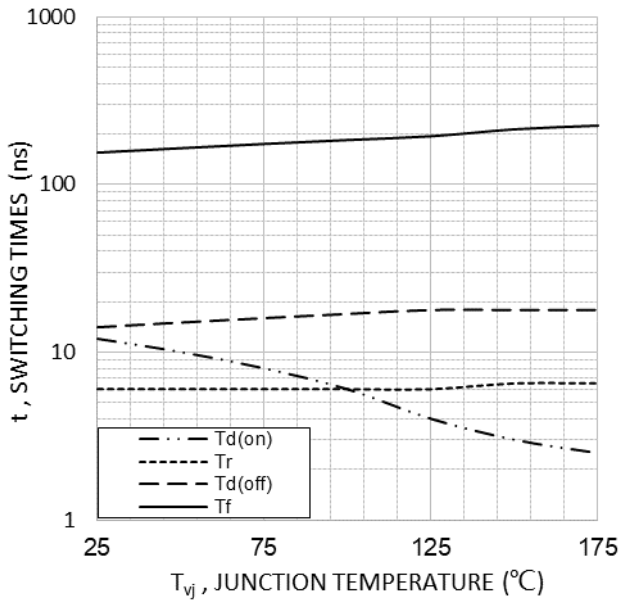


Fig. 9 Typical switching times as a function of junction temperature (inductive load, $V_{CE}=400V$, $V_{GE}=15/0V$, $I_C=6A$, $r_G=10\Omega$)

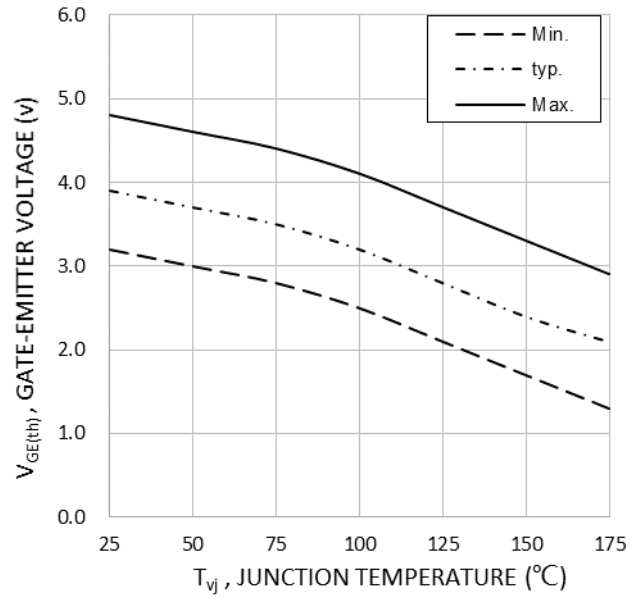


Fig. 10 Gate-emitter threshold voltage as a function of junction temperature ($I_C=0.2mA$)

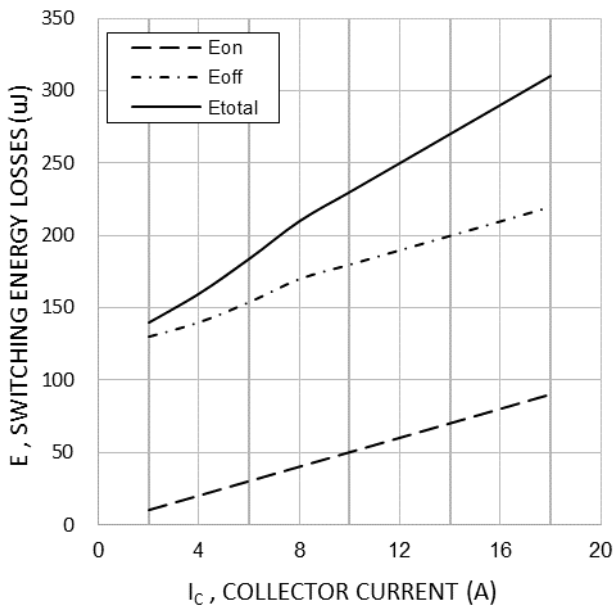


Fig. 11 Typical switching energy losses as a function of collector current (inductive load, $T_{j}=25^{\circ}C$, $V_{CE}=400V$, $V_{GE}=15/0V$, $r_G=10\Omega$)

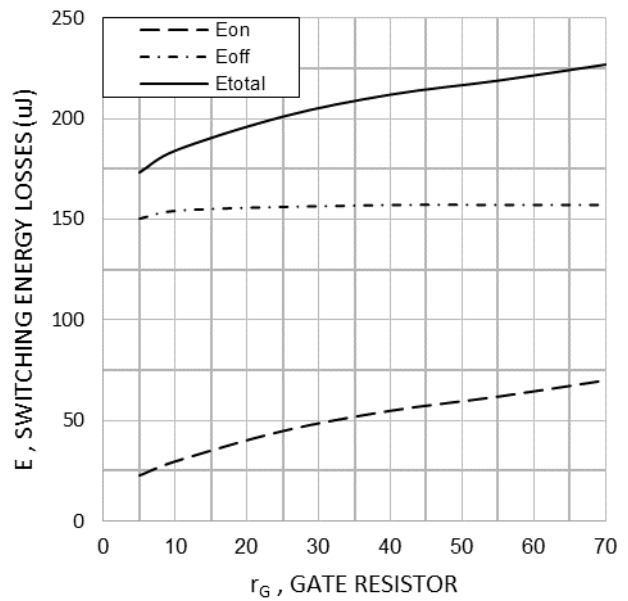


Fig. 12 Typical switching energy losses as a function of gate resistor (inductive load, $T_{j}=25^{\circ}C$, $V_{CE}=400V$, $V_{GE}=15/0V$, $I_C=6A$)

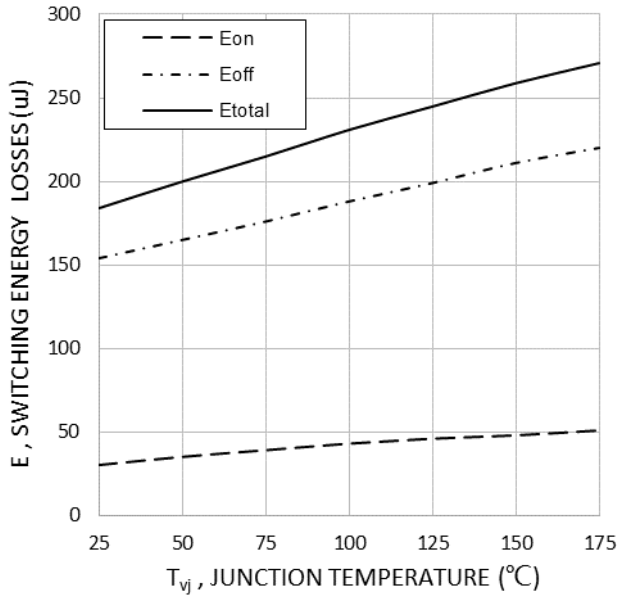


Fig. 13 Typical switching energy losses as a function of junction temperature (inductive load, $V_{CE}=400V$, $V_{GE}=15/0V$, $I_C=50A$, $r_G=10\Omega$)

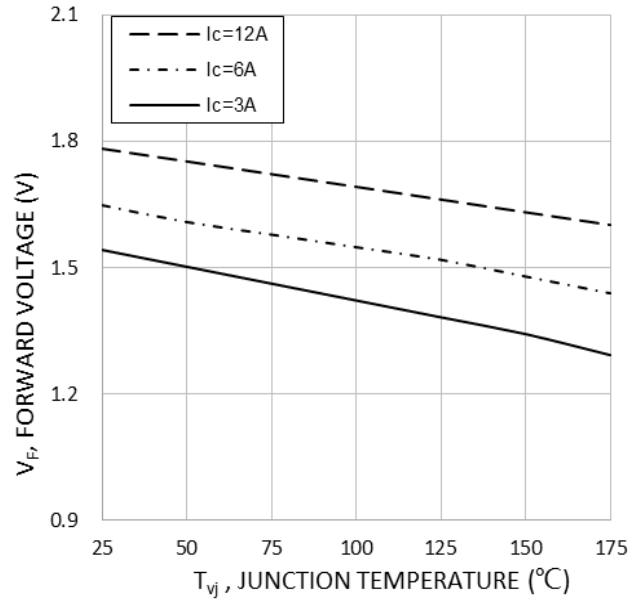


Fig. 14 Typical diode forward voltage as a function of junction temperature

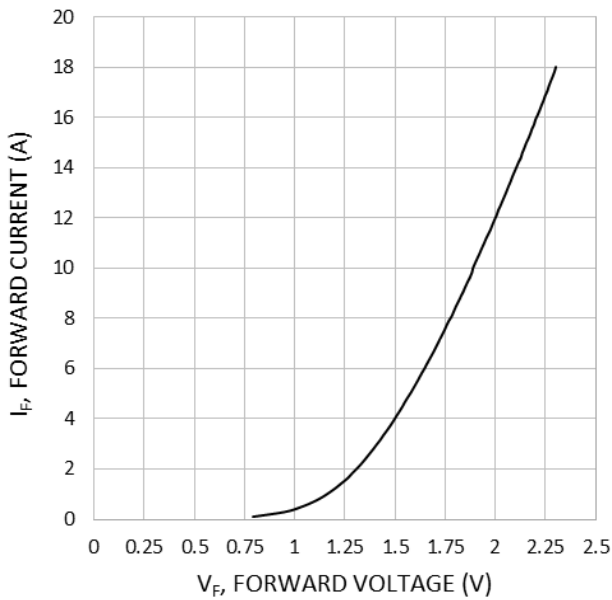


Fig. 15 Typical diode forward current as a function of forward voltage

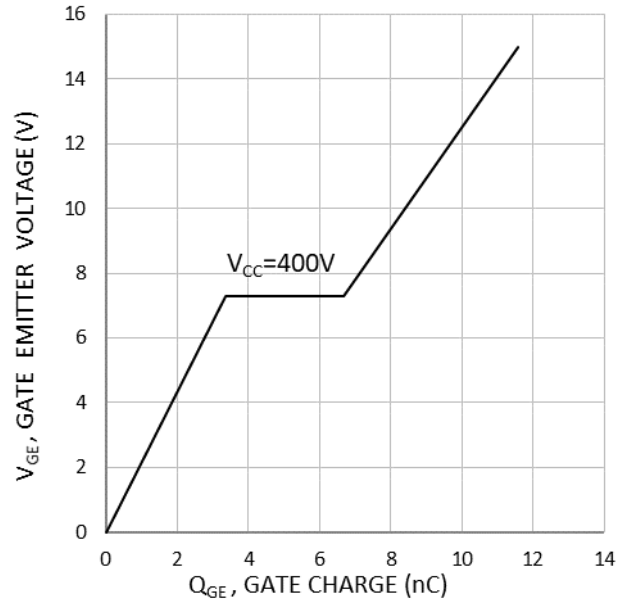


Fig. 16 Typical gate charge ($I_C=6A$)

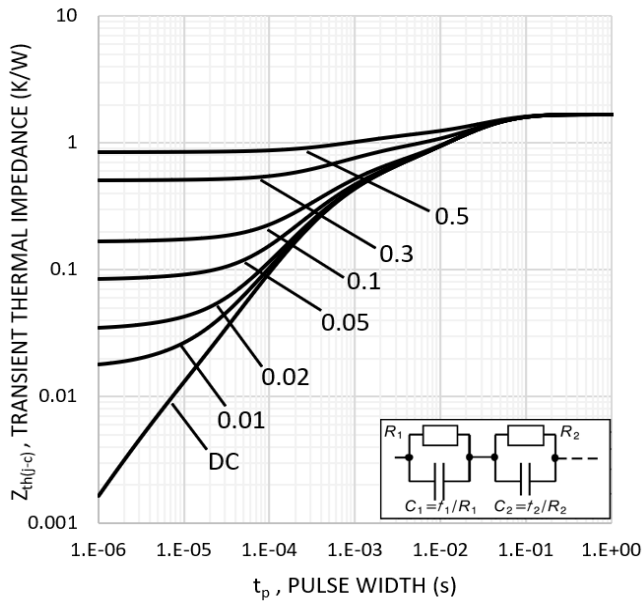


Fig. 17 IGBT transient thermal impedance ($D=t_p/T$) (TO-263)

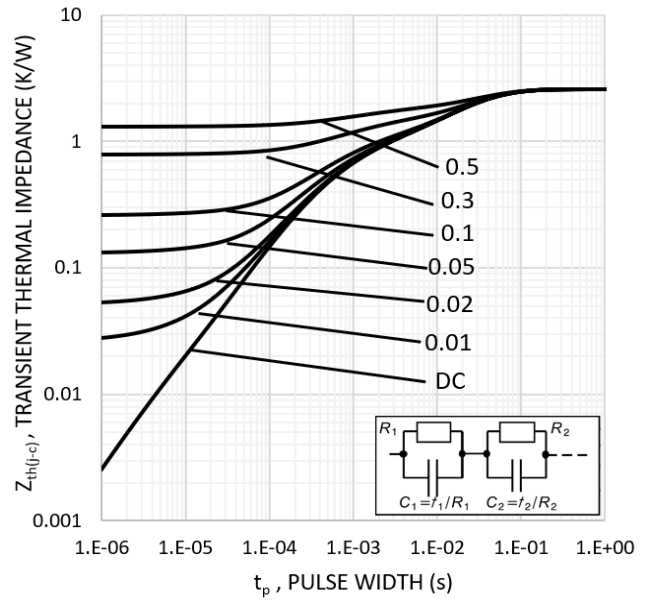
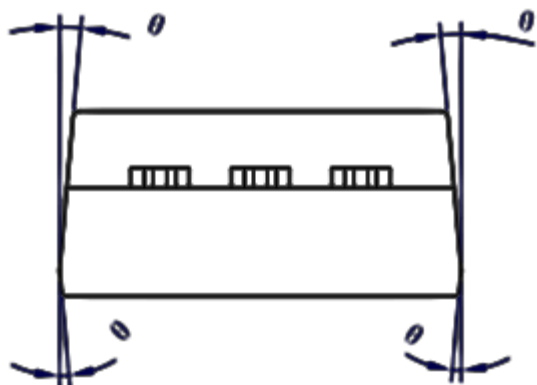
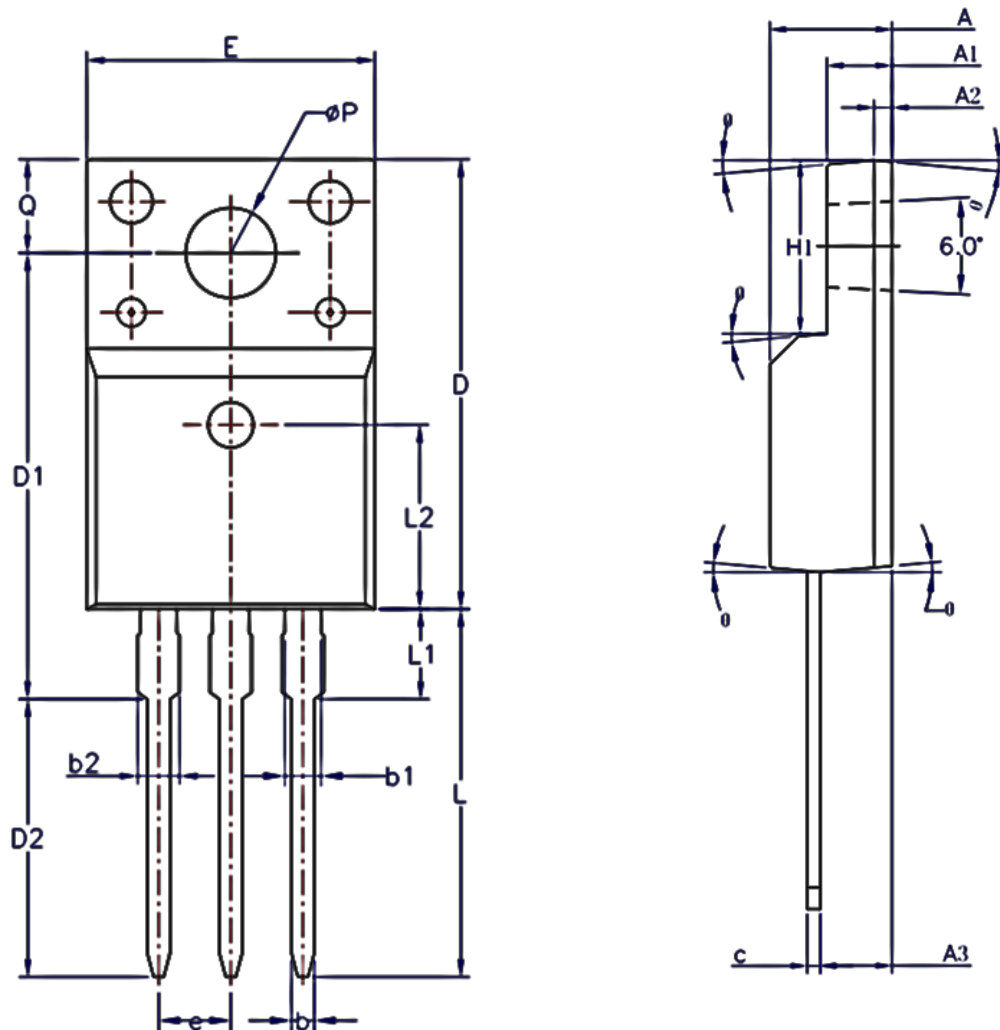


Fig. 18 FRD transient thermal impedance ($D=t_p/T$) (TO-263)

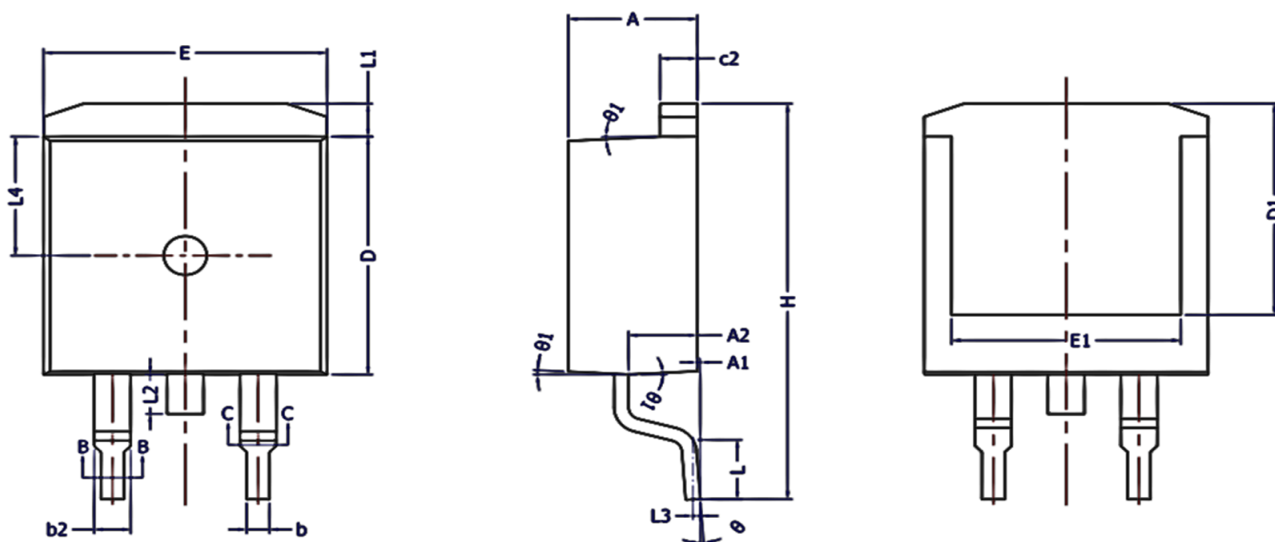
Package Information

TO-220F-3L



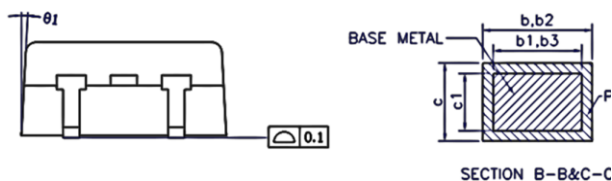
SYMBOL	MIN	NOM	MAX
A	4.50	4.70	4.83
A1	2.34	2.54	2.74
A2	0.70 REF		
A3	2.56	2.76	2.93
b	0.70	-	0.90
b1	1.18	-	1.38
b2	-	-	1.47
c	0.45	0.50	0.60
D	15.67	15.87	16.07
D1	15.55	15.75	15.95
D2	9.60	9.80	10.0
E	9.96	10.16	10.36
e	2.54BSC		
H1	6.48	6.68	6.88
L	12.68	12.98	13.28
L1	-	-	3.50
L2	6.50REF		
ϕP	3.08	3.18	3.28
Q	3.20	-	3.40
$\theta 1$	1°	3°	5°

TO-263-2L



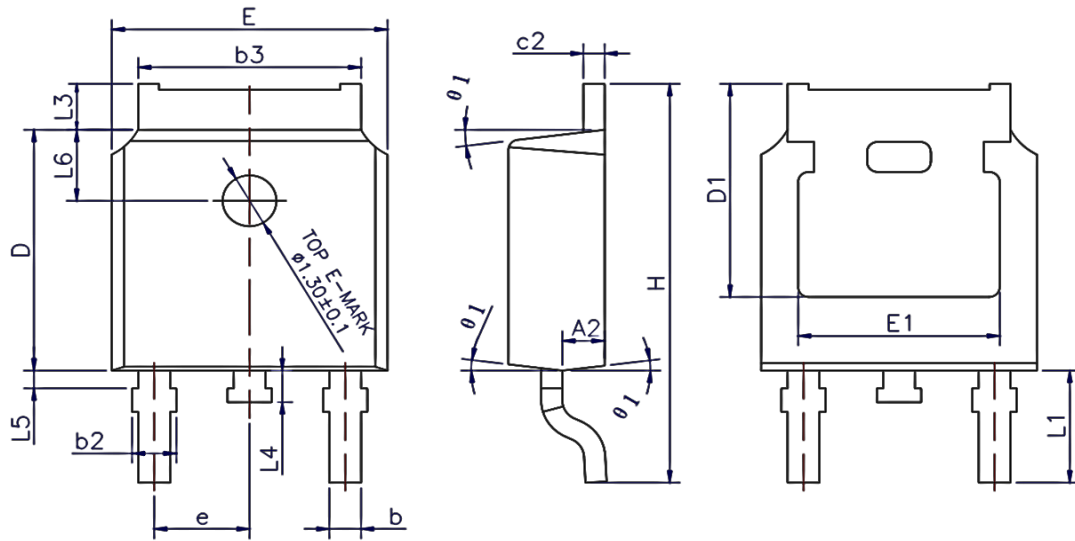
COMMON DIMENSIONS
(UNITS OF MEASURE =MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	0	0.10	0.25
A2	2.20	2.40	2.60
b	0.76	---	0.89
b1	0.75	0.80	0.85
b2	1.23	---	1.37
b3	1.22	1.27	1.32
c	0.47	---	0.60
c1	0.46	0.51	0.56
c2	1.25	1.30	1.35
D	9.10	9.20	9.30
D1	8.00	---	---
E	9.80	9.90	10.00
E1	7.80	---	---
e	2.54 BSC		
H	14.90	15.30	15.70
L	2.00	2.30	2.60
L1	1.17	1.27	1.40
L2	---	---	1.75
L3	0.25BSC		
L4	4.60 REF		
θ	0°	---	8°
θ1	1°	3°	5°



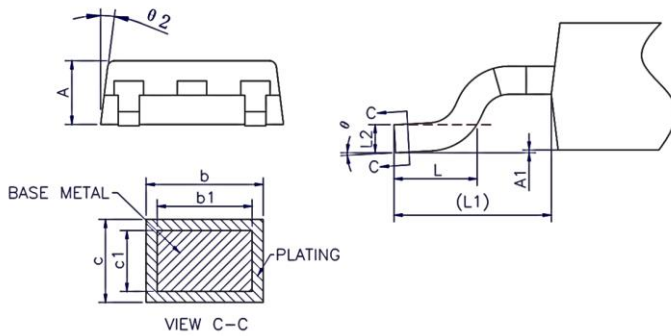
NOTES:
ALL DIMENSIONS REFER TO JEDEC STANDARD TO-263 AB
DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

TO-252-2L



COMMON DIMENSIONS
(UNITS OF MEASURE =MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0	---	0.10
A2	0.90	1.01	1.10
b	0.72	---	0.85
b1	0.71	0.76	0.81
b2	0.72	---	0.90
b3	5.13	5.33	5.46
c	0.47	---	0.60
c1	0.46	0.51	0.56
c2	0.47	---	0.60
D	6.00	6.10	6.20
D1	5.25	---	---
E	6.50	6.60	6.70
E1	4.70	---	---
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.508 BSC		
L3	0.90	---	1.25
L4	0.60	0.80	1.00
L5	0.15	---	0.75
L6	1.80 REF		
θ	0°	---	8°
θ_1	5°	7°	9°
θ_2	5°	7°	9°



NOTES:
ALL DIMENSIONS REFER TO JEDEC STANDARD
TO-252 AA DO NOT INCLUDE MOLD FLASH OR
PROTRUSIONS